



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/756,971  
Filing Date ..... January 9, 2001  
Inventor ..... Salman Akram  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2827  
Examiner ..... D.A. Zarneke  
Attorney's Docket No. ..... MI22-1572  
Title: Methods of Forming Board-On-Chip Packages

### **RESPONSE TO MARCH 5, 2003 OFFICE ACTION**

To: Mail Stop Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

From: D. Brent Kenady  
Tel. 509-624-4276; Fax 509-838-3424  
Wells St. John P.S.  
601 West First Avenue, Suite 1300  
Spokane, WA 99201-3828

Responsive to the Office Action dated March 5, 2003, Applicant amends and remarks as follows:

### **AMENDMENTS**

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.

EV317133724